

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.06861	100.0	1.43
Subtotal				0.06861	100	1.43
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.0061	10.0	0.12718
	Silver alloy	Silver (Ag)	7440-22-4	0.00122	2.0	0.02544
	Lead alloy	Lead (Pb)	7439-92-1	0.0537	88.0	1.11919
Subtotal				0.06102	100	1.27181
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.02575	100.0	0.53677
Subtotal				0.02575	100	0.53677
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00705	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.0047	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00705	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.02585	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	23.45554	99.81	488.8594
Subtotal				23.50019	100	489.79001
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.24791	100.0	5.167
Subtotal				0.24791	100	5.167
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	2.2829	3.0	47.58
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.56579	6.0	95.16
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	7.60965	10.0	158.6
	Carbon Black	Carbon black	1333-86-4	0.38048	0.5	7.93
	Filler	Misc. Silica compounds (generic)	14808-60-7	59.35527	78.0	1237.08
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	1.90241	2.5	39.65
Subtotal				76.0965	100	1586
Total				99.99998	100	2084.19559

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